

PCN Number:	20190920000	PCN Date:	Oct. 2, 2019
Title:	Datasheet for LMK00804B-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



LMK00804B-Q1

SNAS784B – MARCH 2019 – REVISED AUGUST 2019

4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (June 2019) to Revision B

Page

• Changed part-to-part skew maximum from: 700 ps to: 550 ps	1
• Changed front long range radar application to: forward-facing long range radar	1
• Changed <i>Simplified Schematic</i> graphic.....	1
• Changed pin 2 in the RGT package from: OE to: NC	3
• Changed the pin descriptions.....	3
• Changed Changed CDM ESD ratings from: +/-250 V to: +/-750 V.....	4
• Added the <i>Typical Characteristics</i> section back to the data sheet.....	8
• Changed <i>Differential Input Level</i> timing diagram	9
• Changed the <i>Overview</i> section	10
• Changed <i>Functional Block Diagram</i>	10
• Added the <i>Typical Connection Diagram</i>	12
• Changed the <i>Power Considerations</i> section to <i>Power Dissipation Calculations</i>	16
• Moved the <i>Thermal Management</i> section to <i>Do's and Don'ts</i>	16
• Changed the recommendations for unused output pins	17
• Changed the <i>Input Slew Rate Considerations</i> section.....	17
• Added content to the <i>Ground Planes</i> section.....	18
• Changed the <i>Layout Example</i> section.....	19

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMK00804B-Q1	SNAS784A	SNAS784B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LMK00804B-Q1>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
LMK00804BQWRGTRQ1	LMK00804BQWRGTTQ1		

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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